



Jonas & Redmann

„SMART MOVE“

WAFER INSPECTION SYSTEM

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The WIS combines wafer quality control with classification using customer defined inspection tools. Its modular design allows individual extensions and integration into production lines.



WAFER INSPECTION SYSTEM

The Wafer Inspection System checks silicon wafers in a completely automated process. Wafer quality is determined using latest inspection technology. Inspection criteria can be individually adjusted (within given limitations) by choosing the according inspection tools. Furthermore preferred upper and lower levels for measured values can be set up. Those wafers that do not fulfil the defined criteria are automatically sorted into stacking boxes. Wafers then can be reused or disposed. The different inspection and sorting processes are controlled via one single operator panel.

The production process is not interrupted by the inspection system – modules can be integrated into production prior to single production steps.

TECHNICAL DATA

throughput rates of up to 3000 wafers/hr. and more depending on chosen inspection tools

adaptable to wafer sizes 125 × 125 and 156 × 156

suitable for wafer thickness 130 to 300 µm

other formats and thicknesses upon request

FEATURES

remote control to register wafers via barcode scanning

integrated control cabinets

standard communication interface to established MES

one central operator panel with 2 monitors and keyboards

optional bypass lines with buffer function

compatible with a wide range of inspection tools

MODULAR CONFIGURATION

1–3 unstacking modules each with 4 magazines à 400 wafers

checking module for geometry, breakage, surface, sawmarks, TTV, microcrack, specific resistivity, lifetime

checking modul for electronic silicon quality, surface topography, sawmarks, mechanical stability

offspec module for sorting out wafers into stacking boxes

1–3 stacking modules each with 4 magazines à 400 wafers

Technical data are not binding. Changes reserved.